Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

IPC-1752-1 v1.02 **1752-1**	IPC Web Site for Information on IPC-1752 Standard **http://www.ipc.org/IPC-175x**	**Form Type *** **Distribute**	**Declaration Class *** **Class 4 - RoHS Yes/No, JIG Format Substances, Mfg Info**

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	**Response Date ***	Response Document ID	
Anaren Microwave, Inc.			**2007-10-04**		
Contact Name *	Title - Contact	**Phone - Contact ***	**Email - Contact ***	Duplicate Contact -> Authorized Representative	
Michael Lugert	**Product Line Manager**	**(315) 432-8909 x480**	**mlugert@anaren.com**		
Authorized Representative *	Title - Representative	**Phone - Representative ***	**Email - Representative** *	Supplier Comments or URL for Additional Information	
Michael Lugert	**Product Line Manager**	**(315) 432-8909 x480**	**mlugert@anaren.com**		

	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
		11303-3	**3dB Xinger Coupler, 0.38-0.52**			**East Syracuse**	**0.89**	**g**	**Each**
	Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Tin/Lead (Sn63Pb37)	**CU Alloy**	**1**	**260** C	**30** seconds	

Comments

*** Required Field**

CAS Registry Number(R) is a Registered Trademark of the American Chemical Society

Form enabled by Adobe

Save the fields in this form to a file [Export Data] Import fields from a file into this form [Import Data] Clear all of the fields on this form [Reset Form] Lock the fields on this form to prevent changes [Lock Supplier Fields]

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2002/95/EC	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Enter your statement here: See Attachment Below

RoHS Declaration *	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any	Supplier Acceptance	**Accepted**

Exemptions: The items on this form meet the specifications of the RoHS Definition above, except for the following application-specific exemptions. Check the appropriate boxes below for the applicable exemptions for the item.

- ☐ **1**. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp
- ☐ **2a.** Mercury in straight flourescent lamps for general purposes not exceeding 10 mg iin halophosphate lamps
- ☐ **2b**. Mercury in straight flourescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal lifetime
- ☐ **2c**. Mercury in straight flourescent lamps for general purposes not exceeding 8 mg in triphosphate with long lifetime
- ☐ **3**. Mercury in straight flourescent lamps for special purposes
- ☐ **4**. Mercury in other lamps not specifically mentioned in this list
- ☐ **5**. Lead in glass of cathode ray tubes, electronic components and flourescent tubes
- ☐ **6a**. Lead as an alloying element in steel containing up to 0.35% lead by weight
- ☐ **6b**. Lead as an alloying element in aluminum containing up to 0.4% lead by weight
- ☐ **6c.**. Lead as an alloying element in copper containing up to 4% lead by weight
- ☐ **7a**. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead)
- ☒ **7b**. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications
- ☐ **7c**. Lead in electronic ceramic parts (e.g. piezoelectronic devices)
- ☐ **8.** Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending. Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances
- ☐ **9.** Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators
- ☐ **10a.** DecaBDE in polymeric applications
- ☐ **10b.** Lead in lead-bronze bearing shells and bushes
- ☐ **11**. Lead used in compliant pin connector systems
- ☐ **12**. Lead as a coating material for a thermal conduction module c-ring
- ☐ **13a**. Lead in optical and filter glass
- ☐ **13b**. Cadmium in optical and filter glass
- ☐ 14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight
- ☐ **15**. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature	Michael Lugert	Digitally signed by Michael Lugert DN: cn=Michael Lugert, o=Anaren Microwave, ou=Wireless Engineering, email=mlugert@anaren.com, c=US Date: 2008.01.09 10:09:55 -05'00'	

*** Required Field**

Joint Industry Guide (JIG) Material Composition Declaration for Electronic Products

Instructions: Declare whether the item substances exceed the threshold levels shown in the table and report accordingly. Where threshold levels include the words "intentionally added", substances must be declared if they are added intentionally, regardless of threshold level. For each RoHS substance, identified with dual asterisks (**), report the worst case PPM at the homogeneous material level and optionally the total weight of the substance in the item. For all remaining (non-RoHS) JIG A & B substances, and any additional substances, report the total weight and optionally the PPM at the part level for each item.

JIG A autofill - No | JIG B autofill - No | All autofill - No

JIG	Category Name	Threshold Level	Above Threshold Level?	If yes, enter total weight and worse case PPM			Description of Use
Level	**As defined in the Joint Industry Guide**	**Intentionally added or PPM**	**Yes/No**	**Weight**	**UoM**	**PPM**	
A	Asbestos	Intentionally Added	**No**		**mg**		
A	Certain Azo colorants	Intentionally Added	**No**		**mg**		
A	Cadmium/Cadmium Compounds **	75 PPM or Intentionally Added	**No**		**mg**		
A	Hexavalent Chromium/Hexavalent Chromium Compounds **	1000 PPM or Intentionally Added	**No**		**mg**		
A	Lead/Lead Compounds **	1000 PPM or Intentionally Added	**Yes**	**0.0099**	**g**	**11,208**	**Tin/Lead Plating**
A	Lead/Lead Compounds - PVC Cables and Wires Only **	300 PPM	**No**		**mg**		
A	Mercury/Mercury Compounds **	1000 PPM or Intentionally Added	**No**		**mg**		
A	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)	Intentionally Added	**No**		**mg**		
A	Ozone Depleting Substances - Class II (HCFCs)	1000 PPM	**No**		**mg**		
A	Polybrominated Biphenyls (PBBs) **	1000 PPM or Intentionally Added	**No**		**mg**		
A	Polybrominated Diphenylethers (PBDEs) **	1000 PPM or Intentionally Added	**No**		**mg**		
A	Polychlorinated Biphenyls (PCBs)	Intentionally Added	**No**		**mg**		
A	Polychlorinated Naphthalenes (> 3 chlorine atoms)	Intentionally Added	**No**		**mg**		
A	Radioactive Substances	Intentionally Added	**No**		**mg**		
A	Certain Shortchain Chlorinated Paraffins	Intentionally Added	**No**		**mg**		
A	Tributyl Tin (TBT) and Triphenyl Tin (TPT)	Intentionally Added	**No**		**mg**		
A	Tributyl Tin Oxide (TBTO)	Intentionally Added	**No**		**mg**		
B	Antimony/Antimony Compounds	1000 PPM	**No**		**mg**		
B	Arsenic/Arsenic Compounds	1000 PPM	**No**		**mg**		
B	Beryllium/Beryllium Compounds	1000 PPM	**No**		**mg**		
B	Bismuth/Bismuth Compounds	1000 PPM	**No**		**mg**		
B	Brominated Flame Retardants (other than PBBs or PBDEs)	1000 PPM	**No**		**mg**		
B	Nickel (external applications only)	1000 PPM	**No**		**mg**		
B	Certain Phthalates	1000 PPM	**No**		**mg**		
B	Selenium/Selenium Compounds	1000 PPM	**No**		**mg**		
B	Polyvinyl Chloride (PVC)	1000 PPM	**No**		**mg**		

*** Required Field**

OTHER Material Composition Declaration

Requester Instructions: The requester can optionally include additional substances that must be declared for the item on this form. This is in addtion to JIG Level A and JIG Level B substances. The requester should enter additional substances as well as the threshold levels that specify the substance at the item level.

Supplier Instructions: Explicitly declare whether the item exceed the threshold level by selecting Yes or No. If the maximum concentration of any substance exceeds the threshold levels defined by the requester, then the substance content must be reported in total weight and/or worst case PPM, along with a description of material use.

JIG	Category Name	Threshold Level
Other	As defined by the Requester	Defined by the Requester
+ -		

Add Other Material Composition to JIG Tab

*** Required Field**